

SMALL SIGNAL SCHOTTKY DIODE


 MINIMELF
 (Glass)

DESCRIPTION

General purpose, metal to silicon diode featuring high breakdown voltage low turn-on voltage.

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	100	V
I_F	Forward Continuous Current	150	mA
I_{FRM}	Repetitive Peak Forward Current	350	mA
I_{FSM}	Surge non Repetitive Forward Current	750	mA
P_{tot}	Power Dissipation	150	mW
T_{stg} T_i	Storage and Junction Temperature Range	- 65 to 150 - 65 to 125	°C °C
T_L	Maximum Temperature for Soldering during 15s	260	°C

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
$R_{th (j-l)}$	Junction-leads	300	°C/W

ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
V _(BR)	T _j = 25°C	I _R = 100µA	100			V
V _{F*}	T _j = 25°C	I _F = 0.1mA			0.25	V
	T _j = 25°C	I _F = 10mA			0.45	
	T _j = 25°C	I _F = 250mA			1	
I _{R*}	T _j = 25°C	V _R = 1.5V			0.5	µA
	T _j = 60°C				5	
	T _j = 25°C	V _R = 10V			0.8	
	T _j = 60°C				7.5	
	T _j = 25°C	V _R = 50V			2	
	T _j = 60°C				15	
	T _j = 25°C	V _R = 75V			5	
	T _j = 60°C				20	

DYNAMIC CHARACTERISTICS

Symbol	Test Conditions		Min.	Typ.	Max.	Unit
C	T _j = 25°C	V _R = 0V	f = 1MHz		10	pF
	T _j = 25°C	V _R = 1V			6	

* Pulse test : t_p ≤ 300µs δ < 2%

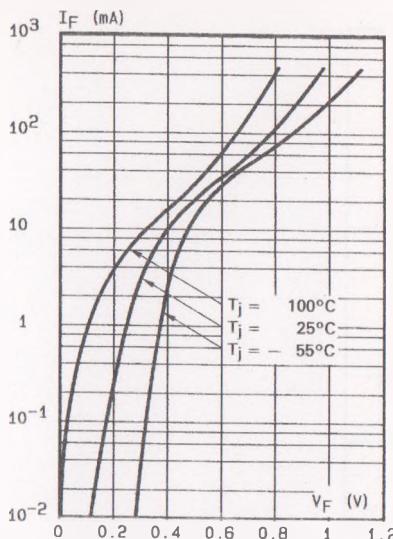


Fig.1 - Forward current versus forward voltage at different temperatures (typical values).

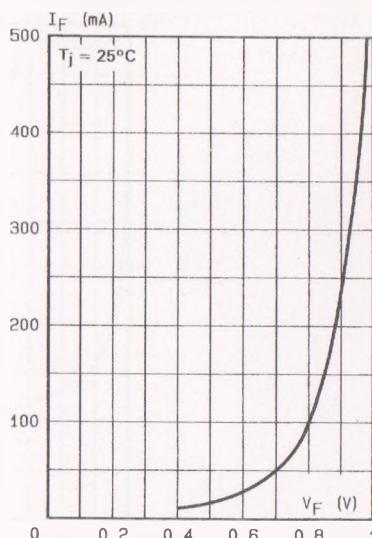


Fig.2 - Forward current versus forward voltage (typical values).

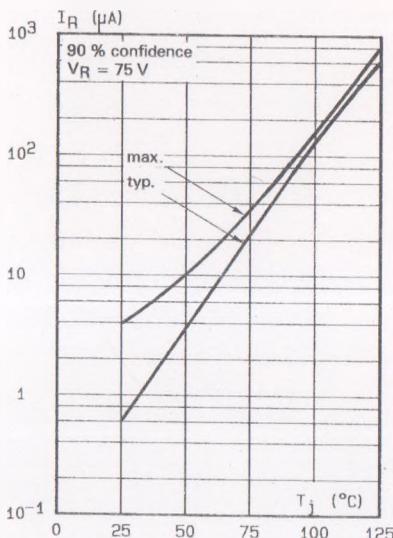


Fig.3 - Reverse current versus junction temperature (typical values).

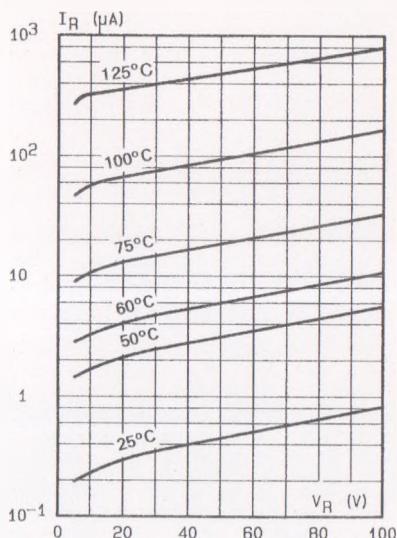


Fig.4 - Reverse current versus continuous reverse voltage.

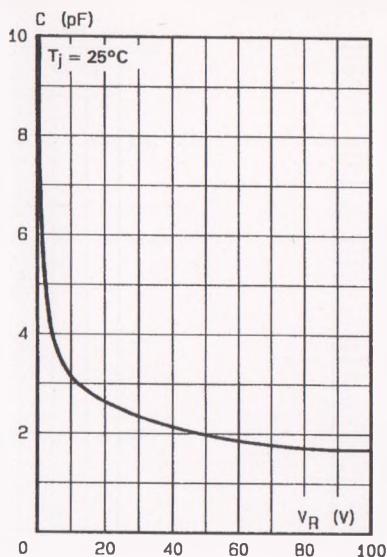


Fig.5 - Capacitance C versus
reverse applied voltage V_R
(typical values).